

# **Product Change Notification**



Product Group: Vishay Siliconix/ October 10, 2016/PCN-SIL-0362016

### Copper Wire Bonding and Additional Back End Capacity for Vishay Siliconix for MLP3.5 x 4.5 packages

**DESCRIPTION OF CHANGE:** Vishay Siliconix has qualified copper wire bonding for 3.5 x 4.5 MLP package parts. Vishay Siliconix also expanded the backend capacity with Subcontractor Amkor in Philippines for the assembly and Siliconix facility, IMI, for the test and Tape and reel, in addition to the already qualified Vishay Taiwan facility.

There is no change to the product form, fit, function and reliability with the above.

CLASSIFICATION OF CHANGE: Material Set Conversion, Capacity Expansion

**REASON FOR CHANGE:** Copper bond-wire conversion program

EXPECTED INFLUENCE ON PERFORMANCE/QUALITY/RELIABILTY: There will be no effect on

performance, quality or reliability.

PRODUCT CATAGORY: ICs

PART NUMBERS AFFECTED: SIC530CD-T1-GE3, SIC531CD-T1-GE3, SIC531ACD-T1-GE3,

SIC532CD-T1-GE3.

VISHAY BRAND(s): Vishay-Siliconix

TIME SCHEDULE: Shipment of products will begin January 11, 2017

SAMPLE AVAILABILITY: Please contact your regional Vishay Sales office for sample availability.

**QUALIFICATION DATA:** Included in this PCN

This PCN is for notification purposes only. Your response is not required. If you have any questions, please contact your local Vishay Sales Office.

ISSUED BY: Isabelle Ciacchella, Vishay Siliconix IC Product Marketing.

E-mail address: isabelle.ciacchella@Vishay.com

For further information, please contact your regional Vishay office.

The Americas

Vishay Americas 2201 Laurelwood Road Santa Clara, Ca 95004 T: 408-970-8000 F: 408-567-8942

business-americas@vishay.com

Europe

Vishay Electronic GmbH Geheimrat-Rosenthal-Strasse 100 D-95100 Selb, Germany T: 49-9287-71 0 F: 49-9287-70435 Asia

Vishay Intertechnology Asia Pte. Ltd 25 Tampines Street 92 #02-00 Keppel Building Singapore 528877 T: 65-6788-6668 F: 65-6788-0988

business-asia@vishay.com

Vishay Intertechnology, Inc.

Europe@vishay.com



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#### **SIC530 Copper Bondwire Qualification Test Results**

#### TABLE 1 - DETAILED RELIABILITY TEST RESULTS

EVAL ***** 1680421	STRESS *******	STEP ****	TEST CONDITION	HR-CYC *****	S <u>S</u> ****	FAIL ****		TEST TYPE ****	FAIL CODE ****
1000421	PRECON	0	PRODUCT PRECO	0	164	0	X	ET	
		1	PRODUCT PRECO	168	164	0	X	ET	
	TEMP CYCLE	0	-55C to +150C	0	82	0	Х	ET	
		1	-55C to +150C	250	82	-0	Х	ET	
		2	-55C to +150C	500	82	0	X	ET	
		3	-55C to +150C	1000	82	0	Х	ET	
	HAST	0	130C, 85%RH	0	82	0	Х	ET	
		1	130C, 85%RH	100	82	0	Х	ET	
	CSAM	1	LEVEL1, CSAM	NA	11	0	Х	ET	
	HTOL	0	Tj=150C	0	82	0	Х	ET	
		1	Tj=150C	168	82	0	X	ET	
	DPA	0		NA	40	0	Х	ET	
	VALIDATION	0	POST PRECON	NA	3000	0	Х	ET	
		1	3X REFLOW	NA	3000	0	X	ET	
		2	-55C to +150C	250	3000	0	X	ET	

PART NUMBER: SIC530

GEOMETRY: ISL95808/NSYW25/NSSY25

LOT #: EBR 1A

PURPOSE: SIC530 [NSYW25 + NSSY25 + ISL95808] USING 1.2MIL APCC (AU-PD COATED COPPER) WIRE (NON-BSOB ON LEADPOST) BONDS IN POWERPAK MLP4.5X3.5 22L PINS PACKAGE, ASSEMBLED

AT AMKOR - PHILIPPINES

Vishay Intertechnology, Inc.